



LP-USM150

Surface mount fuses

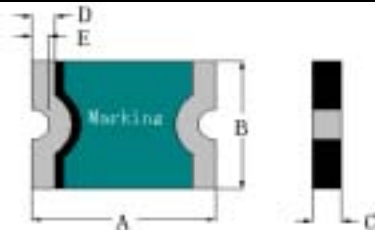
Features

- Smaller size of 1210
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV

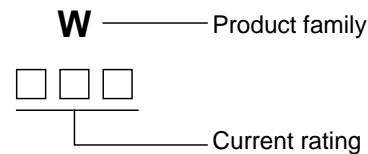


Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-USM150	3.43	2.80	2.25	0.60	0.20



Part Marking System

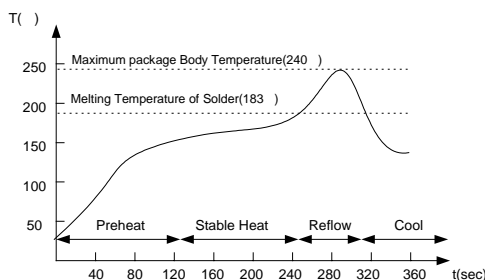
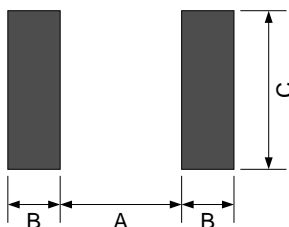


Electrical Characteristics

Part number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} Current(A) Time(S)	Pd _{typ} (W)	R _{min} ()	R _{1max} ()
LP-USM150	1.50	3.00	6	40	8.0 0.50	1.0	0.04	0.11

I_H=Hold current: maximum current at which the device will not trip at 25 still air.
 I_T=Trip current: minimum current at which the device will always trip at 25 still air.
 V_{max}=Maximum voltage device can withstand without damage at rated current.
 I_{max}=Maximum fault current device can withstand without damage at rated voltage.
 T_{trip}=Maximum time to trip(s) at assigned current.
 Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
 R_{min}=Minimum device resistance at 25 prior to tripping.
 R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-USM150	2.00	1.00	2.50

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 3000pcs per reel.